To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):
   Chi-Chuan WU
   Chien-Ping HUANG

   Additional names(s) of conveying party(ies) □ Yes □ No

3. Nature of conveyance:
   □ Assignment □ Merger
   □ Security Agreement □ Change of Name
   □ Other

   Execution Date: August 15, 2001

4. Application number(s) or patent numbers(s):
   If this document is being filed together with a new application, the execution date of the application is: January 30, 2002

   Patent Application No. Filing date

   Additional numbers □ Yes □ No

5. Name and address of party to whom correspondence concerning document should be mailed:
   Name: Peter F. Corless
   Registration No. 33,860
   Address: EDWARDS & ANGELL, LLP
            P.O. Box 9169

   City: Boston State/Prov.: MA
   Country: USA ZIP: 02209

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): $ 40.00
   □ Enclosed - Any excess or insufficiency should be credited or debited to deposit account
   □ Authorized to be charged to deposit account

8. Deposit account number:
   04-1105

   To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

   Peter F. Corless
   Name of Person Signing

   Signature

   January 30, 2002
   Date

   Total number of pages including cover sheet, attachments, and

   Mail documents to be recorded with required cover sheet information to:
   Commissioner of Patents & Trademarks, Box Assignments
   Washington, D.C. 20231

   REEL: 012552 FRAME: 0357
ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar ($1.00) in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

1) Chi-Chuan WU
2) Chien-Ping HUANG

hereby sell, assign and transfer to

SILICONWARE PRECISION INDUSTRIES CO., LTD.
No. 123, Sec. 3, Da Fong Rd., Tantzu, Taichung, Taiwan, R.O.C.

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

SEMICONDUCTOR PACKAGE AND FABRICATING METHOD THEREOF

which application was

a) executed by the undersigned on the day of 19

b) filed on the day of 19

Serial No.

including any and all United States Letters Patents which may be granted thereon and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said Assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date

Signed at TAICHUNG

this 15th day of AUGUST, 2001

INVENTOR(S):

1. Chi-Chuan WU

Chien-Ping HUANG

WITNESSES:

RECORDED: 01/30/2002

PATENT
REEL: 012552 FRAME: 0358